



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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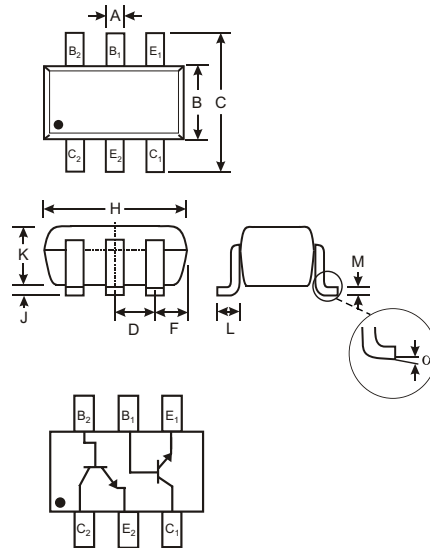


Features

- Epitaxial Planar Die Construction
- Complementary PNP Type Available (IMT4)
- Small Surface Mount Package
- Also Available in Lead Free Version

Mechanical Data

- Case: SOT-26, Molded Plastic
- Case material - UL Flammability Rating Classification 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Also Available in Lead Free Plating (Matte Tin Finish). Please see Ordering Information, Note 4, on Page 2
- Terminal Connections: See Diagram
- Marking (See Page 2): KX8
- Ordering & Date Code Information: See Page 2
- Weight: 0.016 grams (approx.)



SOT-26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
F	—	—	0.55
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	IMX8	Unit
Collector-Base Voltage	V_{CBO}	120	V
Collector-Emitter Voltage	V_{CEO}	120	V
Emitter-Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	50	mA
Power Dissipation (Note 1)	P_d	300	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Operating and Storage and Temperature Range	T_j, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 2)						
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	120	—	—	V	$I_C = 50\mu\text{A}$
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	120	—	—	V	$I_C = 1.0\text{mA}$
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	5.0	—	—	V	$I_E = 50\mu\text{A}$
Collector Cutoff Current	I_{CBO}	—	—	0.5	μA	$V_{CB} = 100\text{V}$
Emitter Cutoff Current	I_{EBO}	—	—	0.5	μA	$V_{EB} = 4.0\text{V}$
ON CHARACTERISTICS (Note 2)						
DC Current Gain	h_{FE}	180	—	820	—	$I_C = 2.0\text{mA}, V_{CE} = 6.0\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	—	0.5	V	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f_T	—	140	—	MHz	$V_{CE} = 12\text{V}, I_E = -2.0\text{mA}, f = 100\text{MHz}$

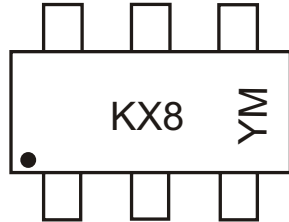
- Notes: 1. Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>. 200mW per element must not be exceeded.
 2. Short duration test pulse used to minimize self-heating effect.

Ordering Information (Note 3)

Device	Packaging	Shipping
IMX8-7	SOT-26	3000/Tape & Reel

- Notes: 3. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.
 4. For Lead Free version (with Lead Free terminal finish) part number, please add "-F" suffix to part number above.
 Example: IMX8-7-F.

Marking Information

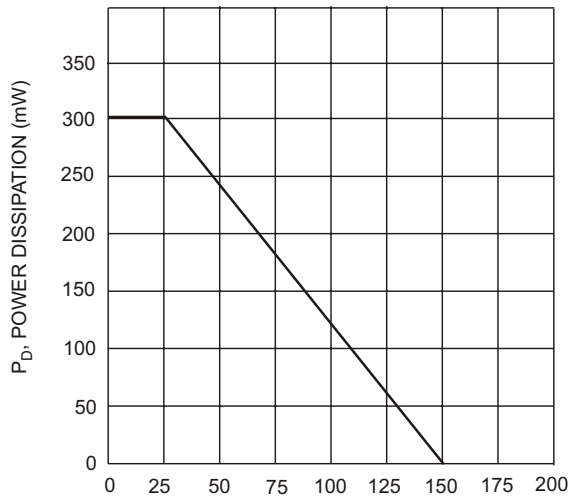


KX8 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: N = 2002
 M = Month ex: 9 = September

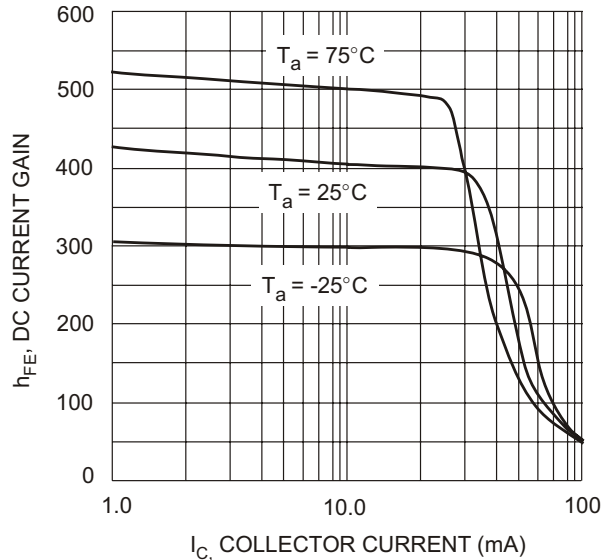
Date Code Key

Year	2002	2003	2004	2005	2006	2007	2008	2009
Code	N	P	R	S	T	U	V	W

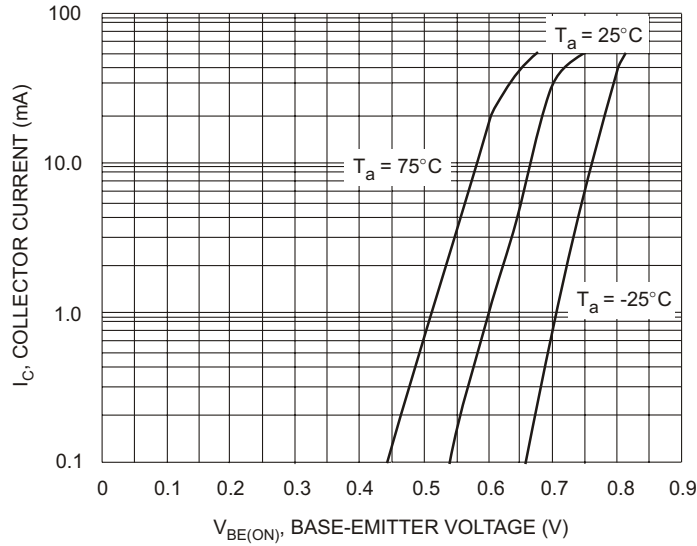
Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D



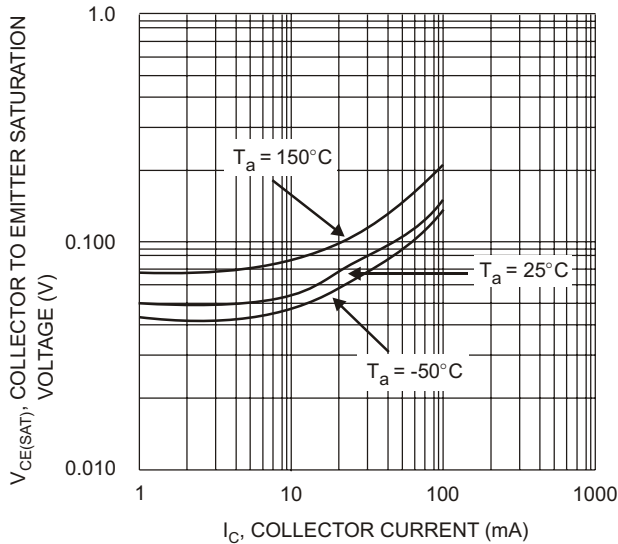
T_A, AMBIENT TEMPERATURE (°C)
 Fig. 1. Max Power Dissipation vs Ambient Temperature



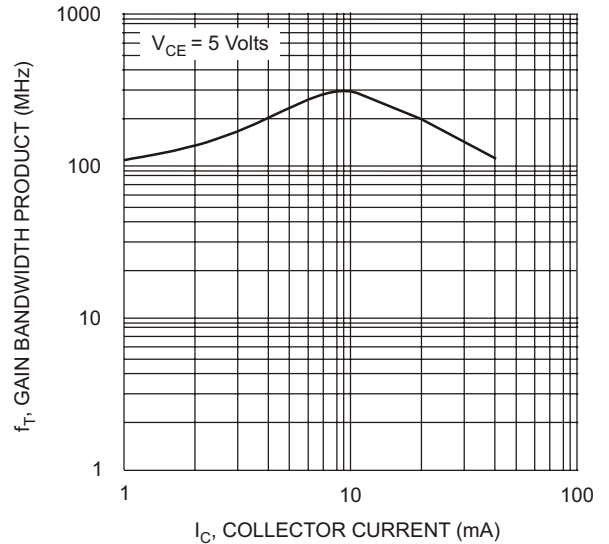
I_C, COLLECTOR CURRENT (mA)
 Fig. 2. Typical DC Current Gain vs. Collector Current



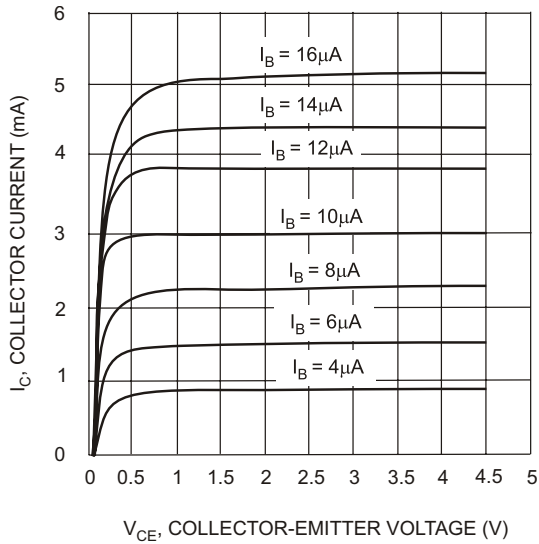
$V_{BE(ON)}$, BASE-EMITTER VOLTAGE (V)
Fig. 3 Typical Collector Current vs. Base-Emitter Voltage



I_C , COLLECTOR CURRENT (mA)
Fig. 4 Typical Collector-Emitter Voltage vs. Collector Current



I_C , COLLECTOR CURRENT (mA)
Fig. 5 Typical Gain Bandwidth Product vs. Collector Current



V_{CE} , COLLECTOR-EMITTER VOLTAGE (V)
Fig. 6 Typical Collector Current vs. Collector-Emitter Voltage